SuperWorkstation A+ Server AS -531AW-TC

UP workstation for AI, design, simulation and media

Key Applications

2D/3D Content Creation, VR Content Development, AI Inference / Training, 3D Rendering, Product Design and Engineering Simulation,

Key Features

- AMD Ryzen™ Threadripper™ PRO 7000WX series and Ryzen™ Threadripper™ 7000 series up to 350W TDP Processors
Supports optional CPU closed-looped liquid cooling kit
CPU and Memory Overclocking supported;
- 4 DDR5 ECC Registered RDIMM/3DS RDIMM, DDR5-5200MHz Up to total 512GB;
- 2 PCIe 5.0 x16 slots and 2 PCIe 5.0 x8 slots, 2 PCIe 4.0 x4 M.2 slots (RAID 0, 1) and 1 MCIO connector (PCIe 4.0 x8) to support 2 NVMe PCIe drives;
- 6 internal fixed 2.5" SATA drive bays and 2 internal fixed 3.5" SATA drive bays;
- 1 Dedicated LAN for IPMI
Dual 10Gb LAN with Broadcom BCM57416;
- 1000W, 1300W and 2000W Power Supply Options;

Form Factor	Mid-Tower Enclosure: 205 x 450 x 470mm (8.07" x 17.72" x 18.5") Package: 325 x 617 x 590mm (12.8" x 24.29" x 23.23")
Processor	Single processor(s) AMD Ryzen™ Threadripper™ PRO 7000X/WX Series Up to 96C/192T; Up to 384MB Cache
GPU	Max GPU Count: Up to 1 quad-width or 2 triple-width or 2 double-width or 2 single-width GPUs Supported GPU: NVIDIA PCIe: NVIDIA RTX PRO™ 6000 Blackwell Workstation Edition, NVIDIA RTX PRO™ 6000 Blackwell Max-Q Workstation Edition, RTX 5000 Ada, RTX 4500 Ada, RTX 6000 Ada Generation
System Memory	Slot Count: 4 DIMM slots/4 Channels Max Memory (1DPC): Up to 512GB 5200MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 8 bays • 2 internal fixed 3.5" SATA* drive bays • 6 internal fixed 2.5" SATA* drive bays Option A: Total 8 bays • 2 internal fixed 3.5" SATA drive bays • 4 internal fixed 2.5" SATA drive bays • 2 internal fixed 2.5" PCIe 4.0 NVMe* drive bays (*NVMe/SATA support may require additional storage controller and/or cables, please see the optional parts list for details) M.2: 2 M.2 PCIe 4.0 x4 NVMe slots (M-key 22110(default)/2280)

Expansion Slots	PCI-Express (PCIe) Configuration: Default
	           • 2 PCIe 5.0 x16 (in x16) FHFL slots
	           • 2 PCIe 5.0 x8 (in x8) FHFL slots
	M.2: 2 M.2 PCIe 4.0 x4 NVMe slots (M-key 22110(default)/2280)

On-Board Devices	Chipset: System on Chip
	Network Connectivity: 2 RJ45 10GbE with Broadcom® BCM57416
	           1 RJ45 1GbE with ASPEED AST2600
	IPMI: Support for Intelligent Platform Management Interface v.2.0
	        IPMI 2.0 with virtual media over LAN and KVM-over-LAN support

Input / Output	LAN: 2 RJ45 10 GBASE-T LAN ports (Broadcom® BCM57416) 1 RJ45 1 GbE Dedicated BMC LAN port (ASPEED AST2600)

USB: 2 USB 3.2 Gen1 Type-A ports(front)
       1 USB 3.2 Gen2 Type-C port(Rear)
       1 USB 3.2 Gen2 Type-C port(Front)
       4 USB 3.2 Gen2 Type-A ports(Rear)
Video: 1 VGA port
Serial: 1 COM port(Rear)
Audio: 7.1 HD Audio
TPM: 1 TPM header

(Front View – System)

USB 3.2 Gen 2x1 (10Gb) Type-C Port
2 USB 3.2 Gen 1x1 (5Gb) Type-A Ports
Power Button
Storage Drive LED Indicator
3.5mm Combo Audio Port

(Rear View – System)

7.1 HD Audio Jacks
COM and VGA Ports
RJ45 1GbE IPMI LAN Port
USB 3.2 Gen 2x2 (20Gb) Type-C Port
4 USB 3.2 Gen 2x1 (10Gb) Type-A Ports
2 RJ45 10GbE LAN Ports

Slot Description	
PCIe 5.0 x16 FHFL	
PCIe 5.0 x8 FHFL	

System Cooling	Fans: 1 Rear Exhaust Fan 120mm Fan(s) 3 Front Intake 120mm Fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	1x 1000W Gold Level (90%) power supply
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!; IPMICFG; SMCIPMITool; IPMIView
PC Health Monitoring	FAN: Status monitor for speed control Voltage: Monitors CPU Core Voltages, +3.3V, +12V, +3.3Vstb, +5Vstb, Vcore, Vmem Temperature: Monitoring for CPU and chassis environment; CPU Thermal Trip Support; I²C Temperature Sensing Logic
Dimensions and Weight	Weight: Gross Weight: 19.2 lbs (8.7 kg) Net Weight: 14.1 lbs (6.4 kg) Available Color: Black
Operating Environment	RoHS Compliant Operating Temperature: 10°C to 30°C (50°F to 86°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	**Super H13SRA-TF**
Chassis	**CSE-GS3A-000NBP**